DECL. TION FOR PATENT APPLICATION (WITH POWER ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM INCLUDING SAME, the specification of which (check one):

_	1 States application serial no. 09/933,297			•
was filed on as PCT intern	national application no and	was amended under PC	Article 19 on	 •
I hereby state that I have reviewed and und referred to above.	derstand the contents of the above-identif	ied specification, includ	ing the claims, as am	ended by any amendment
I acknowledge the duty to disclose to the Umatter claimed in this application, as "materia			be material to the p	atentability of the subject
I hereby claim foreign priority benefits un	der Title 35. United States Code. 8 1190	a)-(d) or 8 365(b) of any	foreign application(s	i) for patent or inventor's
certificate or § 365(a) of any PCT internations attached continuation page and have also ident PCT international application(s) designating at	al application(s) designating at least one diffied below and on any attached continua	country other than the U	nited States of Ameri oplication for patent of	ica listed below and on any or inventor's certificate or ar
which priority is claimed.				
Prior foreign/PCT application(s):			Dei	ority Claimed
200104675-4 (number)	Singapore (country)	06/08/2001 (day/month/year		X Yes No
(number)	(country)	(day/month/year	filed)	res No
I hereby claim the benefit under Title 35, idesignating the United States of America listed application is not disclosed in any such prior a duty to disclose to the U.S. Patent and Traden Regulations § 1.56 which became available be	I below and on any attached continuation pplication in the manner provided by the park Office all information known to me	page and, insofar as the first paragraph of Title to be material to patents	e subject matter of ea 35, United States Co ability as defined in T	ach of the claims of this ode, § 112, I acknowledge th Title 37, Code of Federal
(application serial no.)	(filing date)	(status	- pending, patented of	or abandoned)
,		(c		
(application serial no.)	(filing date)	(status	- pending, patented of	or abandoned)
I hereby claim the benefit under Title 35, I	United States Code, § 119(e) of any Unit	ed States provisional app	plication(s) listed belo	ow:
(provisional application no.)	(filing date)	- · · · · · · · · · · · · · · · · · · ·		
I hereby appoint the following Registered P herewith:	ractitioners to prosecute this application	and to transact all busing	ess in the Patent and	Trademark Office connected
David V. Trask, Reg. No. 22,012 Joseph A. Walkowski, Reg. No. 28,765 Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581 Krista Weber Powell, Reg. No. 47,867 Shawn G. Hansen, Reg. No. 42,627 Katherine A. Hamer, Reg. No. 47,628	William S. Britt, Reg. No. 20,969 James R. Duzan, Reg. No. 28,393 Edgar R. Cataxinos, Reg. No. 39,93 Paul C. Oestreich, Reg. No. 44,983 Jarett K. Abramson, Reg. No. 47,3 Bretton L. Crockett, Reg. No. 44,6 Michael L. Lynch, Reg. No. 30,871	H. Dickso Kent S. B. Devin R. J. David L. S. Bradley B.	B. Bond, Reg. No. 3 n Burton, Reg. No. urningham, Reg. No. lensen, Reg. No. 44, Stott, Reg. No. 43,93 Jensen, Reg. No. 44 Brantley II, Reg. No.	P-48,396 30,453 805 17 6,801
	ley B. Jensen, telephone no. (801) 532-1	922.		*
P.O.	BOX 2550 Lake City, Utah 84110		•	
I hereby declare that all statements made he not further that these statements were made with, under Section 1001 of Title 18 of the Unissued thereon.	th the knowledge that willful false staten	ents and the like so ma	de are punishable by	fine or imprisonment, or
ull name of first joint inventor: Setho Sing Fe	* 22	Date	0/29/01	
desidence: Singapore Citizenship: Republic of Singapore Cost Office Address: Block 91, Bedok North Si	treet 4, #11-1523, Singapore 460091		, ,	· · ·

DECLARATION FOR PATENT APPLICATIO (continuation page)

Date

Invention title: QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM **INCLUDING SAME**

Inventor name(s) appearing on first declaration page: Setho Sing Fee

Additional original, first and joint inventor(s):

Full name of second joint inventor: Lim Thiam Chye

Inventor's signature

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